



## Product Information

# Zytel® HTN

high performance polyamide resin

## Zytel® HTNFR52G30LX NC010

30% Glass Reinforced, Flame Retardant, High Performance Polyamide Resin  
for Pb free soldering system

Property	Test Method	Units	FR52G30LX NC010
			Measured at 23 °C D.A.M.
<b>Mechanical</b>			
Stress at Break	ISO 527	MPa	181
Strain at Break	ISO 527	%	2.5
Tensile Modules	ISO 527	MPa	10,000
Notched Charpy Impact	ISO 179	KJ/m <sup>2</sup>	13
<b>Thermal</b>			
HDT(.045MPa)	ISO 75-1&2	°C	282
HDT(1.82MPa)			
Melting Temperature	ISO 3146C	°C	311
Density	ISO 1183	Kg/m <sup>3</sup>	1630
<b>Electrical</b>			
Relative Permittivity	IEC 60250	MHz	3.84
Dissipation Factor	IEC 60250		0.015
Ark Resistance	UL746A	V	113
Dielectric Strength	IEC 60243-1	KV/mm	24.2
Volume Resistivity	IEC 60093	ohm	1.48x10 <sup>15</sup>
Surface Resistivity	IEC 60093	ohm	3.67x10 <sup>15</sup>
<b>Processing</b>			
Resin Temp		°C	325-330
Molding Temp		°C	60-130
Dry Condition			100C x 6Hrs
Processing Moisture Content		%	<0.1

Contact DuPont for Material Safety Data Sheet, general guides and/or additional information about ventilation, handling, purging, drying, etc.  
ISO Mechanical properties measured at 4.0mm, ISO Electrical properties measured at 2.0mm, and all ASTM properties

**The above data are preliminary and are subject to change as additional data are developed on subsequent lots.**

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